

End of Life

Dual-XMC Carrier for Development and Testing

Please contact X-ES Sales



- ATX power connector
- XMC support
- Onboard oscillator
- Local reset switch
- Status LEDs

XTend2001

The XTend2001 is a dual-XMC carrier card designed to provide a low-cost and compact platform for XMC modules. The XTend2001, in conjunction with a standard off-the-shelf ATX power supply, provides a complete desktop or benchtop platform for development, evaluation, and testing.

The XTend2001 is ideal for testing high-speed I/O available on the P15 and P16 XMC connectors. The SerDes transmit signals from the primary XMC are routed directly to the SerDes receive signals on the secondary XMC and vice versa. The XTend2001 also routes the two VITA 42.10 10/100/1000 Mbps Ethernet ports from P16 to RJ-45 jacks for easy access. Serial I/O from P16 is routed to a mini-DB-9 connector on the XTend2001. The XTend2001 is powered using a standard ATX power supply. The 3.3 V rail is fed directly to the XMC 3.3 V power pins. A factory build option allows the user to supply either 5 V or 12 V to the XMC's VPWR power pins.

The XTend2001 also features JTAG test support through two Addressable Scan Port (ASP) JTAG devices, which isolate each XMC onto its own JTAG chain for maximum test speed and isolation. A 7x2 header is provided for use with boundary scan test equipment, such as ASSET Intertech's PCI-400.



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XMC

- Point-to-point connectivity between XMC 0 and XMC 1
- 100 MHz reference clock provided to each XMC site

Power Supplies

• Power supplied directly from ATX connector

Environmental Requirements

Contact factory for appropriate board configuration based on environmental requirements.

- Supported ruggedization levels (see chart below): 1
- Conformal coating available as an ordering option

Ruggedization Level	Level 1
Cooling Method	Standard Air-Cooled
Operating Temperature	0 to +55°C ambient †
Storage Temperature	-40 to +85°C ambient
Vibration	0.002 g²/Hz (maximum), 5 to 2000 Hz
Shock	20 g, 11 ms sawtooth
Humidity	Up to 95% non-condensing

[†] Contact factory for airflow rate details.



